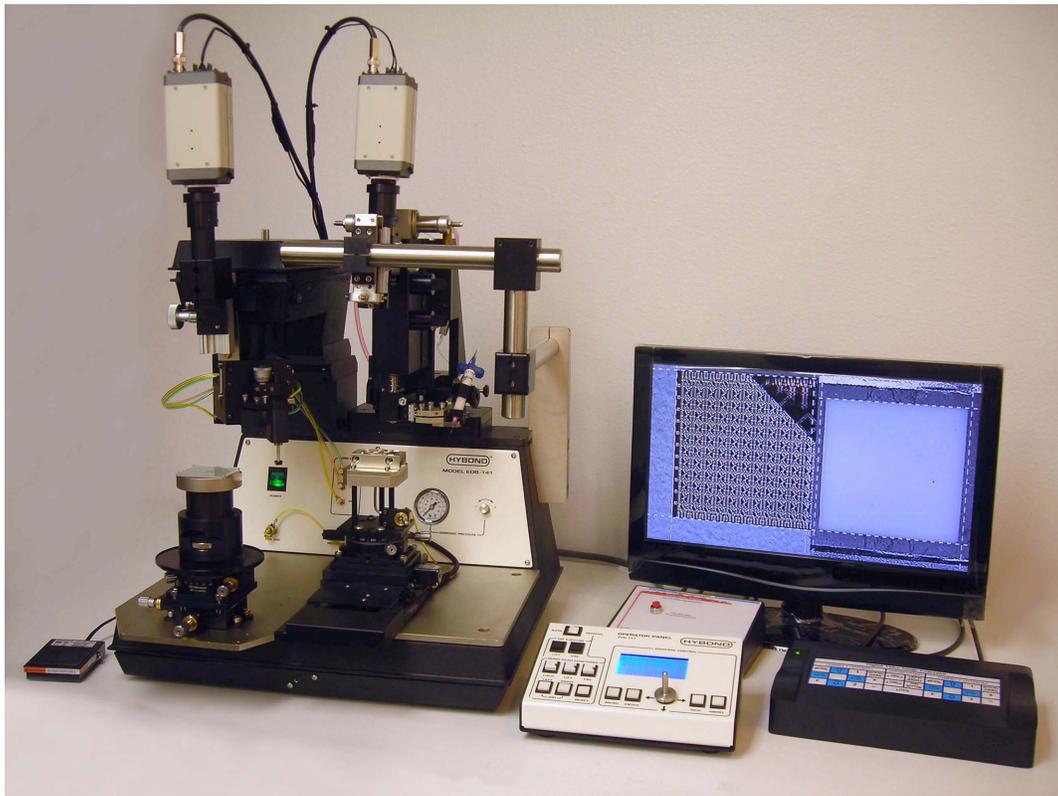


HYBOND

MODEL EDB-141 EPOXY/SILVER GLASS DIE BONDER



STANDARD FEATURES:

- Color CCTV system (as shown).
- Package depth sensing for consistent and precise bond line thickness.
- Built-in programmable dispense control.
- Storage for up to 200 dispense programs.
- Motorized/programmable X-Y stage.
- Waffle pack/loose die pick up pedestal.
- Pitch and roll adjustment for bond head.
- Custom die collets to match customer die.
- Manual and semi-automatic operation modes.
- Remote control panel for ease of operation.
- **Programmable Epoxy dispense patterns.**

HYBOND's EDB-141 is a semiautomatic die bonder that provides uniform epoxy or silver glass dispensing in various programmable dispense patterns with consistent adjustable material bond line thickness and precise die placement. The EDB-141 has a motorized X-Y placement stage for programming single or multi-dispense and placement locations and a manual die pick up pedestal for holding waffle pack/jel pack or loose die or can be fitted with a die ejector for holding die on wafers. The dispense system can be fitted with HYBOND's micro-dispense head for extremely low volume epoxy dispensing. This machine is rugged enough for continuous production and ideal for small to medium production runs and laboratory applications. Die pick up and placement are made easy with the aid of dual CCTV cameras and a split screen monitor which incorporates a dual visual targeting system. The EDB-141 is modular and can be modified to accommodate custom packages.

Partial List of Available Options:

- Die ejector systems.
- Vacuum die pedestal for gel packs.
- Zoom stereo microscope with swivel base.
- Dual fiber optic illumination system.
- Stir column for silver glass/conductive epoxy.
- Micro-dispensing head.
- Lead frame indexing systems.
- Semi-automatic indexing systems.
- Heater stage and temperature controller.
- Customization based on specific application.

Model EDB-141 Specifications:

- Dispense System: Programmable pressure, time and suck-back (avoids drip) system.
- Bond Line Accuracy: +/-0.5mil (+/-12,7um).
- Temperature Control Range: Ambient. Ambient to 250° C with optional heat stage.
- Bondable Die Size Range: 6x6 mils (152x152um) to 1x1in (25x25mm) standard.
- Placement Accuracy: +/-1mil (+/-25,4um) standard. Less when adding microscope option.
- Dispense Materials: Epoxy, conductive Epoxy and silver glass.
- Bond Head Movement: Motorized, rotational with fixed pickup and placement points.
- Bond Actuation: By opto-sensor at fixed height. Cycle initiated by footswitch.
- Z Travel/Vertical Bonding Window: 0.5in. (12mm)/0.125 to 0.500 in (3,18mm to 12mm).
- Table Motion: Motorized/programmable ± .78” (20mm) travel, standard.
- Input Power Requirements: 120 VAC 50/60Hz @ 10A max., for 240VAC requires 600-065.
- Minimum Bench Space Required: Height/width: 24in. (61cm), Depth: 22in. (56cm), without monitor.
- Facilities Required (minimum): Vacuum: 23in.Hg (584mmHg). Air: 60psi (4,2Kg/cm⁵).
- Unit Weight/Shipping Weight: 75lbs (34Kg)/150lbs (68Kg). Shipping weight will vary.
- Approximate Units Per Hour (UPH): 90 - 240 depending on options, settings and mode of operation.

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